Tool ID: 802
Tool Location: 224

Equipment Information Sheet

Dicing Saw - DISCO

Manager: Sam Wright 607-254-4836
Backup: Michael Skvarla 607-254-4674
Backup: John Treichler 607-254-4949

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- Do not operate with open covers

USAGE RESTRICTIONS

- No buddy system restrictions apply
- Check with tool manager for wafers thicker than 1 mm

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 30 minutes

- Maximum 2 hour reservation limit

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No GaAs substrates allowed.

Last Updated: 06/18/2025